

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	780	(PSA (pressure near5 sensitive near5 adhesive)) near10 (insulat\$3 dielectric)	US-PGPU B; USPAT; USOCR	OR	ON	2005/02/19 12:25
L3	241	2 and peel\$3	US-PGPU B; USPAT; USOCR	OR	ON	2005/02/19 12:26
L4	45	3 and (wafer chip semiconductor)	US-PGPU B; USPAT; USOCR	OR	ON	2005/02/19 12:18
L5	341	(PSA (pressure near5 sensitive near5 adhesive)) near10 (insulat\$3 dielectric)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/02/19 12:26
L6	875	(PSA (pressure near5 sensitive near5 adhesive)) and (insulat\$3 dielectric)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/02/19 12:26
L7	875	5 6	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/02/19 12:26
L8	73	7 and peel\$3	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/02/19 12:26